	OPERATING				STORAGE				
RATING	TEMPERATU	JRE RANGE	-35°C TO +85°C (NOTES 1)		TEMPERATUR	RE RANGE	-10°C TO +60°C(I	NOTES 3)
	OPERATING HUMIDITY RA		20% TO 80% (NOTE	ES 2)	STORAGE HUMIDITY RA	NGE	40% TO 70% (N	IOTES 3)	3)
	VOLTAGE		30V AC		APPLICABLE	CONNECTOR	DF36A-50S-0). 4V	
			F		APPLICABLE	CABLE			#40
	CURRENT		AWG#42:0. 2!		TIONS		THIN COAXIAL CABL	_⊏ (AWG	#42
				JITICA	I ION2			<u> </u>	Т
	TEM		TEST METHOD			REC	QUIREMENTS	QT	A
CONSTRI	XAMINATION	MELIALLY	AND BY MEASURING INSTRI	LIMENT	IACCOF	RDING TO DRA	NA/INIC		_
JARKING	XAMINATION		ED VISUALLY.	UNENT.	ACCOR	DING TO DRA	AVVING.	X	; ;
	IN/IENITAL /	CHARACTE						^	
SALT MIST				48 h	INO DEF	FECT SUCH A	S CORROSION WHICH		Τ
JALI WIOT		LXI OSLD	EXPOSED IN 5 % SALT WATER SPRAY 48 h.				TION OF CONNECTOR.	Х	_
SULFUR DIOXIDE GAS		EXPOSED	EXPOSED IN 10-15 PPM 96h.				S CORROSION WHICH FION OF CONNECTOR.	х	-
RESISTANCE TO		-	①BONDING TEMPERATURE:				OF CASE OF EXCESSIVE		
SOLDERING	HEAT		IAX :5 sec MAX IIN :30 sec MAX		LOOSE	ENESS OF THE	E TERMINALS.	X	-
		2MANUAL	IIN :30 SEC MAX _ SOLDERING TEMPERATUR ISEC MAX.	E:					
SOLDERABILITY		SOLDERE	SOLDERED AT SOLDER TEMPERATURE, 230°C FOR INSERTION DURATION, 3 sec.				ER A MINIMUM OF ACE BEING IMMERSED.	X	Τ.
	LUDE THE TEI	MPERATURE F	ON OF REVISIONS		DESIGNED	APPROVED	CHECKED TS. SAKATA	10.0	ATE
EMARKS OTE1: INCL OTE2: NON OTE3: APP BEF	LUDE THE TEI I CONDENSIN PLY TO THE ORE PCB OF	MPERATURE F IG CONDITION O N BOARD,AFT	RISING BY CURRENT F LONG TERM STORAGE F ER PCB BOARD , OPERAT	ING TEMP	ED PRODUCTS ERATURE AND	CHECKED	TS. SAKATA TS. FUKUSHIMA	10. ()3. 1)3. 1
REMARKS IOTE1: INCL IOTE2: NON IOTE3: APP BEF HUM	LUDE THE TEI I CONDENSIN PLY TO THE ORE PCB OF MIDITY RANGE	MPERATURE F IG CONDITION O N BOARD,AFT E IS APPLIED F	RISING BY CURRENT F LONG TERM STORAGE F	ING TEMP	ED PRODUCTS ERATURE AND	CHECKED	TS. SAKATA TS. FUKUSHIMA KT. ISHII	10. (03. 1 03. 1
EMARKS IOTE1: INCL IOTE2: NON IOTE3: APP BEF HUM	LUDE THE TEI I CONDENSIN PLY TO THE ORE PCB OI MIDITY RANGE wise specified,	MPERATURE F IG CONDITION O N BOARD,AFT E IS APPLIED F refer to JIS C \$	RISING BY CURRENT F LONG TERM STORAGE F ER PCB BOARD, OPERAT FOR INTERIM STORAGE DUR	ING TEMP	ED PRODUCTS ERATURE AND	CHECKED DESIGNED DRAWN	TS. SAKATA TS. FUKUSHIMA	10. (10. (10. (03. 1 03. 1
EMARKS IOTE1: INCL IOTE2: NON IOTE3: APP BEF HUM	LUDE THE TEI I CONDENSIN PLY TO THE ORE PCB OI MIDITY RANGE wise specified,	MPERATURE FIG CONDITION O N BOARD,AFT E IS APPLIED F refer to JIS C S	RISING BY CURRENT F LONG TERM STORAGE F ER PCB BOARD , OPERAT FOR INTERIM STORAGE DUR 5402,IEC60512.	ING TEMP	ED PRODUCTS ERATURE AND SPORTATION.	CHECKED DESIGNED DRAWN	TS. SAKATA TS. FUKUSHIMA KT. ISHII	10. (10. (10. (03. 1 03. 1